

Global Die Attach Film for Advanced Packaging Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Die Attach Film for Advanced Packaging market size is expected to reach \$ 2668 million by 2032, rising at a market growth of 22.1% CAGR during the forecast period (2026-2032).

Die Attach Film for Advanced Packaging refers to thin adhesive film materials used in semiconductor packaging to bond semiconductor dies to substrates, lead frames, interposers, redistribution layers, or other dies in stacked and heterogeneous package structures. Compared with liquid die attach paste, die attach film provides more uniform bondline thickness, better process cleanliness, reduced resin bleed, improved die placement stability, and better compatibility with thin dies and high-density packages. In this report, the market mainly includes non-conductive die attach film, conductive die attach film, dicing die attach film, thermally conductive die attach film, ultra-thin die attach film, wafer-level die attach film, and die attach film for stacked die, fan-out, SiP, memory, logic, and power semiconductor packages. The 2025 benchmark ASP is US\$115 / square meter, shipment volume is 5,600k square meters, and average gross margin is 42%. The upstream industry chain includes epoxy resins, acrylic resins, polyimide resins, curing agents, conductive fillers, thermal conductive fillers, release liners, carrier films, dicing tapes, solvents, specialty additives, and precision coating materials. The midstream includes adhesive formulation, film coating, drying, lamination, slitting, wafer-shape processing, dicing tape integration, thickness control, contamination control, reliability testing, and semiconductor-grade quality inspection. The downstream includes advanced semiconductor packaging, memory packaging, logic packaging, fan-out packaging, system-in-package, 2.5D and 3D packaging, power semiconductor packaging, consumer electronics, automotive electronics, artificial intelligence chips, and data center semiconductors.

Die attach film is becoming more important in advanced packaging because thinner dies, smaller package dimensions, higher interconnect density, and multi-die integration require more precise and cleaner bonding materials. Film-based die attach materials help improve bondline control, reduce adhesive overflow, support wafer-level processing, and improve the reliability of stacked die and high-density packages. Demand is supported by memory stacking, system-in-package, fan-out packaging, high-performance computing chips, automotive electronics, and power semiconductor devices. Product development is moving toward thinner film thickness, stronger thermal performance, lower warpage, lower void formation, better compatibility with laser dicing and wafer-level processing, and improved adhesion to multiple substrate and die surfaces.

This report studies the global Die Attach Film for Advanced Packaging production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Die Attach Film for Advanced Packaging and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Die Attach Film for Advanced Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Die Attach Film for Advanced Packaging total production and demand, 2021-2032, (K Sqm)

Global Die Attach Film for Advanced Packaging total production value, 2021-2032, (USD Million)

Global Die Attach Film for Advanced Packaging production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (K Sqm), (based on production site)

Global Die Attach Film for Advanced Packaging consumption by region & country, CAGR, 2021-2032 & (K Sqm)

U.S. VS China: Die Attach Film for Advanced Packaging domestic production, consumption, key domestic manufacturers and share

Global Die Attach Film for Advanced Packaging production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (K Sqm)

Global Die Attach Film for Advanced Packaging production by Type, production, value, CAGR, 2021-2032, (USD Million) & (K Sqm)

Global Die Attach Film for Advanced Packaging production by Application, production, value, CAGR, 2021-2032, (USD Million) & (K Sqm)

This report profiles key players in the global Die Attach Film for Advanced Packaging market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Molex, TE Connectivity, Amphenol, BizLink, JPC Connectivity, Luxshare Technologies, Foxconn Interconnect Technology, Y.C. Cable, NFSB Tech, JPC Powertech, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Die Attach Film for Advanced Packaging market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Sqm) and average price (US\$/Sq m) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Die Attach Film for Advanced Packaging Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Die Attach Film for Advanced Packaging Market, Segmentation by Type:

Non-Conductive Die Attach Film

Conductive Die Attach Film

Global Die Attach Film for Advanced Packaging Market, Segmentation by Adhesive Chemistry:

Epoxy-Based Die Attach Film

Acrylic-Based Die Attach Film

Polyimide-Based Die Attach Film

Silver-Filled Die Attach Film

Global Die Attach Film for Advanced Packaging Market, Segmentation by Film Thickness:

Ultra-Thin Die Attach Film

Thin Die Attach Film

Standard Thickness Die Attach Film

Thick Die Attach Film

Global Die Attach Film for Advanced Packaging Market, Segmentation by Application:

Advanced Semiconductor Packaging

Consumer Electronics

Automotive Electronics

Artificial Intelligence & High-Performance Computing

Data Center Semiconductors

Companies Profiled:

Molex

TE Connectivity

Amphenol

BizLink

JPC Connectivity

Luxshare Technologies

Foxconn Interconnect Technology

Y.C. Cable

NFSB Tech

JPC Powertech

Key Questions Answered:

1. How big is the global Die Attach Film for Advanced Packaging market?
2. What is the demand of the global Die Attach Film for Advanced Packaging market?
3. What is the year over year growth of the global Die Attach Film for Advanced Packaging market?
4. What is the production and production value of the global Die Attach Film for Advanced Packaging market?
5. Who are the key producers in the global Die Attach Film for Advanced Packaging market?

6. What are the growth factors driving the market demand?

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